

EP579 and EP579-1

Low density epoxy paste

Trelleborg EP579 and EP579-1 are two component epoxy paste systems designed for bonding and repairing Trelleborg epoxy boards. Their low slump properties mean they are particularly suitable for use on vertical surfaces up to 2.5 mm thick. They are easily processable and characterized by good mechanical properties and heat stability.

EP579 and EP579-1 Features & Benefits

- Excellent machinability
- Low slump on vertical surfaces up to 2.5 mm thick
- Low density
- Good mechanical properties
- High heat stability

EP579 and EP579-1 Applications

- EP579 and EP579-1 are designed for epoxy board bonding and repair.

EP579 and EP579-1 Product Sizes

- EP579 and EP579-1 are available in 3.5 kg kits



EP579 and EP579-1 Storage

The EP579 and EP579-1 adhesives and hardeners should be stored in original containers at a temperature between 15 and 25°C. The products may crystallize during storage. If crystallized, warm to 55 - 65°C until dissolution, then mix well. Both components, if stored in the specified conditions, have a shelf life of 12 months from the date of production.

EP579 and EP579-1 Health & Safety

Eye protection and gloves should be worn when working with Trelleborg EP 579 and EP579-1.

Please refer to the Trelleborg MSDS.

PHYSICAL PROPERTIES

Product	EP579 Adhesive	EP579 Hardener	Mixture	EP579-1 Adhesive	EP579-1 Hardener	Mixture
Colour	Blue	Blue	Blue	Blue	Blue	Blue
Mix Ratio (pbw)	100	8		100	12	
Density	660 kg/m ³	980 kg/m ³	720 kg/m ³	660 kg/m ³	980 kg/m ³	720 kg/m ³
Viscosity	Paste	31 mPas	Paste	Paste	31 mPas	Paste
Pot Life* (200g)			25 minutes			80 minutes
Gel Time* (200g)			30 minutes			100 minutes
Curing (1mm/20°C)			5 hrs			5 hrs
Curing (1mm/60°C)			1 hr			1 hr
HDT, post cure			80°C			85°C

* data measured at 20°C

MECHANICAL PROPERTIES EP579 and EP579-1

Shore Hardness	68 D	ISO 868
Flexural Strength	30.3 MPa	ISO 178
Flexural Modulus	2,260 MPa	ISO 178
Tensile Strength	15.4 MPa	ISO 527-1
Deformation at Break	4.1 %	ISO 527-1
Compressive Strength	23.1 MPa	ISO 604
Linear Shrinkage*	0.04%	Internal

*sample 500x50x10mm

EP579 and EP579-1 Processing Guidelines**Preparation of Substrates**

Read the Material Safety Data Sheet before use.

Substrate surfaces must be cleaned and dried to remove traces of dust, dirt, oils or release agent before applying EP579 or EP579-1. If necessary, degrease with 1-bromopropane or other suitable solvent. Models, moulds and parts to be assembled must withstand the recommended post-cure cycle temperature.

Mixing and Application

EP579 and EP579-1 adhesives must be mixed with EP579 or EP579-1 hardener respectively in the exact mix ratio by weight indicated. Both components must be at room temperature (20 – 25°C).

Initially mix for 4 – 5 minutes until the dough is smooth, paying attention to the material on the edges of the container and not to incorporate too much air.

For gluing and repair of epoxy boards intended for applications at elevated temperatures, the use of vacuum is recommended to avoid the retention of any air pockets.

Polymerization and Post-Curing

A full cure is obtained after 72 hours at 20°C but to allow the materials to reach their highest thermal stability, a thermal cycle of 4 hours at 120°C is recommended.

**TRELLEBORG****Trelleborg Advanced Engineering Materials**

Eagle Way, Off Queensway
Rochdale, Lancashire
OL11 1TQ, UK

Tel: +44 (0)1706 716610
Fax: +44 (0) 1706 716611
Email: aem@trelleborg.com

Website: www.trelleborg.com/aem

24 Teed Drive
Randolph, MA 02368
USA

Tel: +1 (774) 719 1400
Fax: +1 (774) 719 1401
Email: aem@trelleborg.com

Website: www.trelleborg.com/offshore-boston

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